

Part Number: **UDZxxxB-(p)-F**  
Weight (mg): 6.127

p = package designator  
See Data Sheet

xxx = 10, 11, 12, 13, 14, 15, 16, 18, 20, 22, 24, 27, 2V0, 2V2, 2V4, 2V7, 30, 33, 36, 39, 3V0, 3V3, 3V6, 3V9, 43, 47, 4V3, 4V7, 51, 56, 5V1, 5V6, 6V2, 6V8, 7V5, 8V2, 9V1

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.85	0.052	1000000	8487
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	33.30	2.04	576500	191947
		Ni	7440-02-0	41.00%			410000	136511
		Mn	7439-96-5	0.60%			6000	1998
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	333
		Co	7440-48-4	0.50%			5000	1665
		Si	7440-21-3	0.15%			1500	499
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.65	0.04	1000000	6528
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.63	0.1	1000000	16321
Encapsulation	CEL-1620HF-9	Silica	60676-86-0	77.00%	58.27	3.57	770000	448654
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	----	11.00%			110000	64093
		Basic Duromer: Phenolic resin (Compound of polymeric network)	----	6.60%			66000	38456
		Misc. system	system	5.00%			50000	29133
		Carbon black	1333-86-4	0.40%			4000	2331
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	5.30	0.325	1000000	53044
					<b>Total</b>	<b>100.00</b>	<b>6.127</b>	<b>1000000</b>

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBD
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Dimethyl fumarate	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Halogens	Radioactive Substances
Hexavalent chromium compounds	Red Phosphorous
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)
REACH SVHCs and other Substances of Concern:	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Anthracene	Bis (2-ethyl(hexyl)phthalate) (DEHP)
4,4'- Diaminodiphenylmethane	Hexabromocyclododecane (HBCDD)
Dibutyl phthalate	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cyclododecane	Bis(tributyltin)oxide
Cobalt dichloride	Lead hydrogen arsenate
Diarsenic pentaoxide	Triethyl arsenate
Diarsenic trioxide	Benzyl butyl phthalate
Sodium dichromate, dihydrate	
Beryllium, Beryllium Alloys and Compounds	Methylene Chloride
Hydrazine	Trichloroethene
Tetrachloroethylene	Methyl Ethyl Ketone
Toluene	Xylenes
Toluene Diisocyanate	